Vishay General Semiconductor



Surface Mount TRANSZORB® Transient Voltage Suppressors



DO-214AA (SMBJ)

3.3 V

600 W

60 A

175 °C

PRIMARY CHARACTERISTICS

V_{WM}

P_{PPM}

I_{FSM}

T_J max.

FEATURES

- Uni-directional polarity only
- Peak pulse power: 600 W (10/1000 $\mu s)$
- Excellent clamping capability
- · Very fast response time
- Meets MSL level 1, per J-STD-020C, LF max peak of 260 °C
- Solder dip 260 °C, 40 seconds
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

TYPICAL APPLICATIONS

Use in sensitive electronics protection against voltage transients induced by inductive load switching and lighting on ICs, MOSFET, signal lines of sensor units specifically for protecting 3.3 V supplied sensitive equipment against transient overvoltages.

MECHANICAL DATA

Case: DO-214AA (SMBJ)
Epoxy meets UL 94V-0 flammability rating
Terminals: Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
E3 suffix for commercial grade, HE3 suffix for high reliability grade (AEC Q101 qualified)
Polarity: Color band denotes cathode end

| MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted) | | | | | | |
|---|-----------------------------------|---------------|------|--|--|--|
| PARAMETER | SYMBOL | VALUE | UNIT | | | |
| Peak pulse power dissipation ⁽¹⁾⁽²⁾ | P _{PPM} | 600 | W | | | |
| Peak pulse current with a 10/1000 μs waveform (Fig. 1) | I _{PP} | 50 | А | | | |
| Peak pulse current with a 8/20 waveform (Fig. 1) | I _{PPM} | 200 | А | | | |
| Non repetitive peak forward surge current 8.3 ms single half sine-wave ⁽²⁾ | I _{FSM} | 60 | А | | | |
| Power dissipation on infinite heatsink, $T_L = 75 \ ^{\circ}C$ | PD | 5 | W | | | |
| Operating junction and storage temperature range | T _J , T _{STG} | - 65 to + 175 | °C | | | |

Notes:

(1) Non-repetitive current pulse, per Fig. 1

(2) Mounted on 0.2 x 0.2" (5.0 x 5.0 mm) copper pads to each terminal

| ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted) | | | | | | | | | | | |
|---|---------|-----|--------------------------|--|-----|---|----|---|-----|---|--|
| DEVICE TYPE | MARKING | | AGE AT I _T | MAXIMUM REVERSE LEAKAGE CURRENT I _R AT V _{WM} MAX | | MAXIMUM CLAMPING VOLTAGE V _C AT I _{PP} 10/1000 µs | | MAXIMUM CLAMPING VOLTAGE V _C AT I _{PPM} 8/20 µs | | TYPICAL TEMP. COEFFICIENT OF V _{BR} | TYPICAL JUNCTION CAPACITANCE C _J AT 0 V 1 MHz |
| | | v | mA | μA | v | V | Α | v | Α | (10 ⁻⁴ /°C) | pF |
| SMBJ3V3 | KC | 4.1 | 1.0 | 200 | 3.3 | 7.3 | 50 | 10.3 | 200 | - 5.3 | 5200 |

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| THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted) | | | | | | |
|--|-----------------------|-------|------|--|--|--|
| PARAMETER | SYMBOL | VALUE | UNIT | | | |
| Typical thermal resistance, junction to lead ⁽¹⁾ | $R_{	extsf{	heta}JL}$ | 20 | °C/W | | | |
| Typical thermal resistance, junction to ambient ⁽²⁾ | $R_{	hetaJA}$ | 100 | °C/W | | | |

Notes:

(1) Thermal resistance from junction to lead - mounted on 0.2 x 0.2" (5.0 x 5.0 mm) copper pads to each terminal

(2) Thermal resistance from junction to ambient - mounted on the recommended P.C.B. pad layout

| ORDERING INFORMATION (Example) | | | | | | |
|--------------------------------|-----------------|------------------------|---------------|------------------------------------|--|--|
| PREFERRED P/N | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE | | |
| SMBJ3V3-E3/52 | 0.096 | 52 | 750 | 7" diameter plastic tape and reel | | |
| SMBJ3V3-E3/5B | 0.096 | 5B | 3200 | 13" diameter plastic tape and reel | | |
| SMBJ3V3HE3/52 ⁽¹⁾ | 0.096 | 52 | 750 | 7" diameter plastic tape and reel | | |
| SMBJ3V3HE3/5B ⁽¹⁾ | 0.096 | 5B | 3200 | 13" diameter plastic tape and reel | | |

Note:

(1) Automotive grade AEC Q101 qualified

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

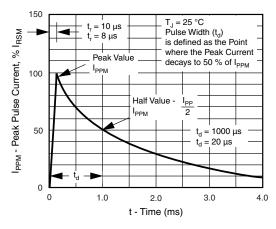
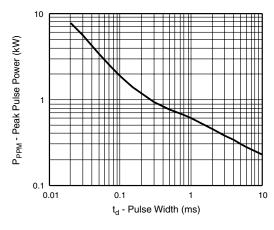


Figure 1. Pulse Waveform





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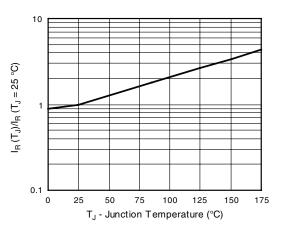
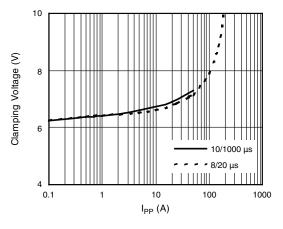
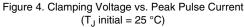


Figure 3. Relative Variation of Leakage Current vs. Junction Temperature





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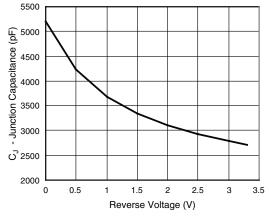


Figure 5. Typical Junction Capacitance

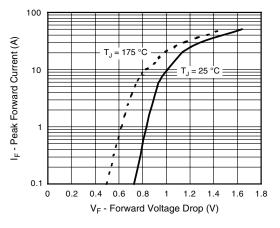


Figure 7. Typical Peak Forward Voltage Drop vs. Peak Forward Current

Mounting Pad Layout

0.220 REF.

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0.060 (1.52) MIN.

0.085 (2.159) MAX.

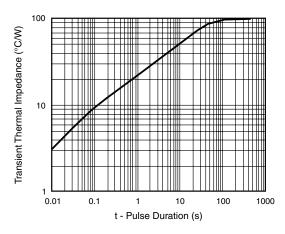


Figure 6. Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214AA (SMB-J-Bend) Cathode Band 0.086 (2.20) 0.155 (3.94) 0.077 (1.95) 0.130 (3.30) 0.086 (2.18) MIN. 0.180 (4.57) 0.012 (0.305) 0.096 (2.44) 0.084 (2.13) 0.060 (1.52) 0.008 (0.2) 0 (0) 0.220 (5.59)

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